

APPLICATION DATA SHEET

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Title of Invention	FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE STRUCTURE
Application Type: regular, utility Attorney Docket Number: 27-035.D1	
Correspondence address: Customer Number: 22898 *22898*	
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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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